

N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY

V _{DS} (V)	R _{DS(on)} (mΩ)(Typ.)	I _D (A) ^a	Q _g (Typ.)
40	1.6 at V _{GS} = 10 V	135	52 nC
	2.8 at V _{GS} = 4.5 V		

FEATURES

- DT-Trench Power MOSFET
- Improved dv/dt Capability
- Fast switching
- Green Device Available

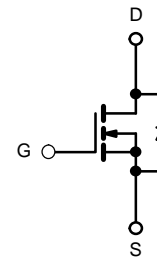
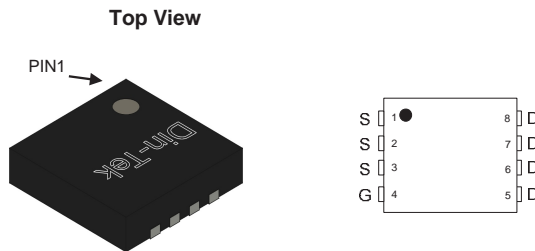


RoHS
COMPLIANT

APPLICATIONS

- Motor Drive
- Power Tools
- LED Lighting
- Quick Charger

DFN3.3X3.3-8L Pin Configuration



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DS}	40	V
Gate-Source Voltage	V _{GS}	± 20	
Continuous Drain Current (T _J = 150 °C) ^a	I _D	T _C = 25 °C	135
		T _C = 100 °C	99
Pulsed Drain Current ^b	I _{DM}	520	A
Single Avalanche Energy	E _{AS}	259	mJ
Maximum Power Dissipation ^c	P _D	T _C = 25 °C	95
		T _C = 100 °C	38
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to +150	°C

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-Ambient (PCB Mount) ^d	R _{thJA}	62	°C/W
Junction-to-Case (Drain)	R _{thJC}	1.3	

Notes

- Calculated continuous current based on maximum allowable junction temperature.
- Repetitive rating; pulse width limited by max. junction temperature.
- P_D is based on max. junction temperature, using junction-case thermal resistance.
- The value of R_{thJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.

SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	40	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.2	-	2.5	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	-	-	± 100	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V	-	-	1	μA
		V _{DS} = 32 V, V _{GS} = 0 V, T _J = 100 °C	-	-	10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	135	-	-	A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A	-	1.6	2.05	mΩ
		V _{GS} = 4.5 V, I _D = 15 A	-	2.8	3.6	
Forward Transconductance ^a	g _{fs}	V _{DS} = 10 V, I _D = 3 A	-	15	-	S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 20 V, f = 1 MHz	-	2950	-	pF
Output Capacitance	C _{oss}		-	1100	-	
Reverse Transfer Capacitance	C _{rss}		-	58	-	
Total Gate Charge ^c	Q _g	V _{DS} = 20 V, V _{GS} = 10 V, I _D = 65 A	-	52	-	nC
Gate-Source Charge ^c	Q _{gs}		-	8.3	-	
Gate-Drain Charge ^c	Q _{gd}		-	14	-	
Gate Resistance	R _g	f = 1 MHz	-	0.9	-	Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = 20 V, I _D = 65 A, R _g = 6 Ω V _{GS} = 10 V	-	10	-	ns
Rise Time ^c	t _r		-	15	-	
Turn-Off Delay Time ^c	t _{d(off)}		-	20	-	
Fall Time ^c	t _f		-	30	-	
Drain-Source Body Diode Ratings and Characteristics ^b (T_C = 25 °C)						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	-	-	135	A
Pulsed Current	I _{SM}		-	-	520	A
Forward Voltage ^a	V _{SD}	I _F = 1 A, V _{GS} = 0 V	-	-	1	V
Reverse Recovery Time	t _{rr}	I _F = 10 A, di/dt = 100 A/μs	-	70	-	ns
Reverse Recovery Charge	Q _{rr}		-	100	-	nC

Notes

- Pulse test; pulse width ≤ 200 μs, duty cycle ≤ 2 %.
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

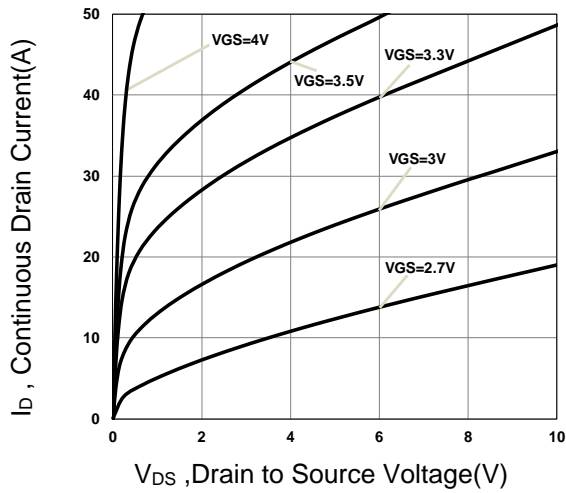


Fig.1 Typical Output Characteristics

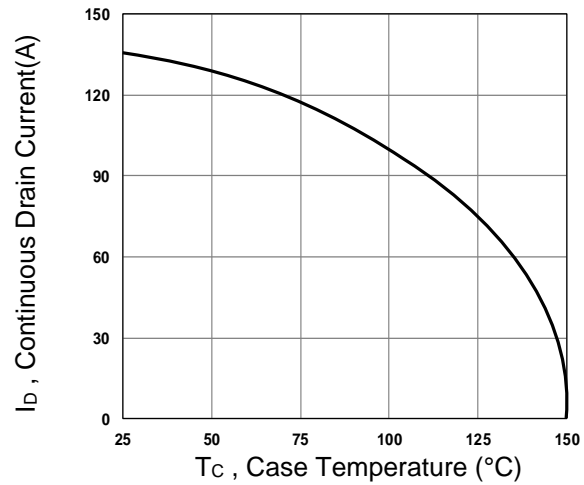


Fig.2 Continuous Drain Current vs. T_c

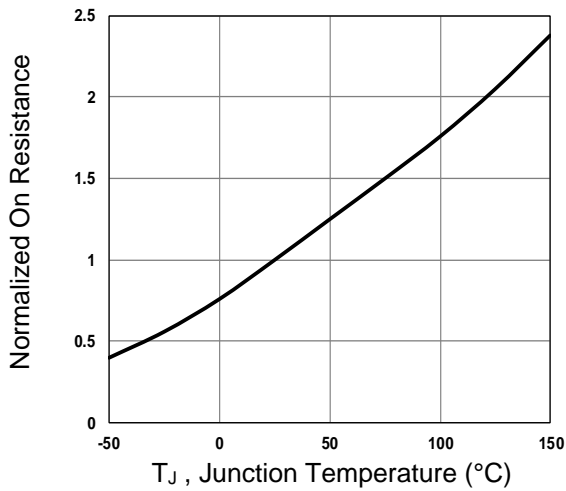


Fig.3 Normalized R_{DS(on)} vs. T_J

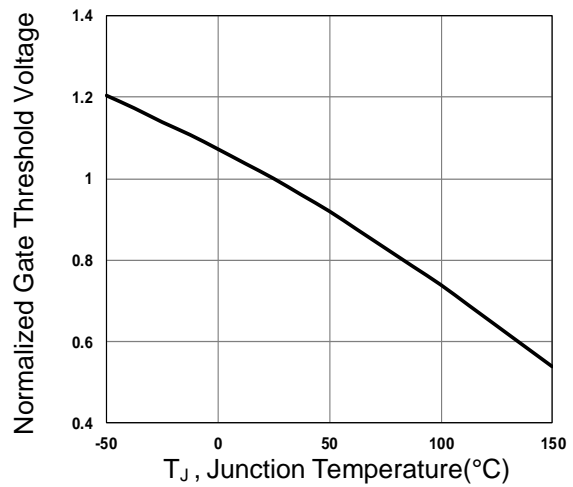


Fig.4 Normalized V_{th} vs. T_J

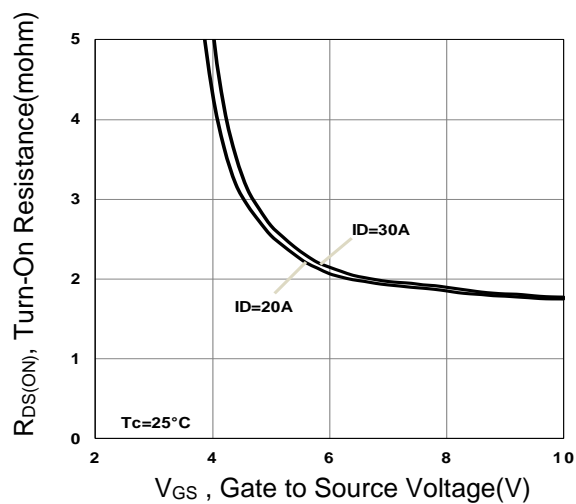


Fig.5 Turn-On Resistance vs. V_{GS}

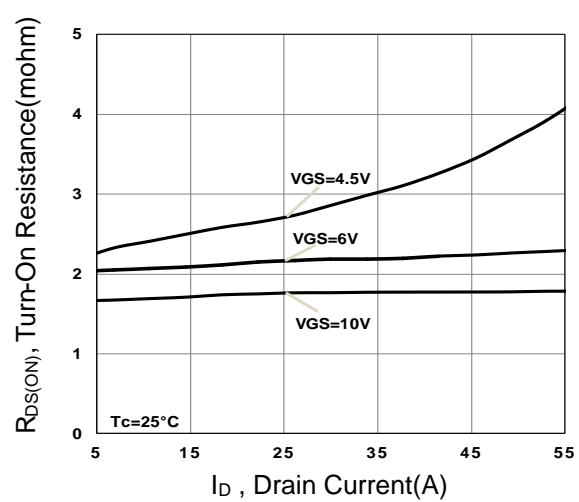


Fig.6 Turn-On Resistance vs. I_D

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

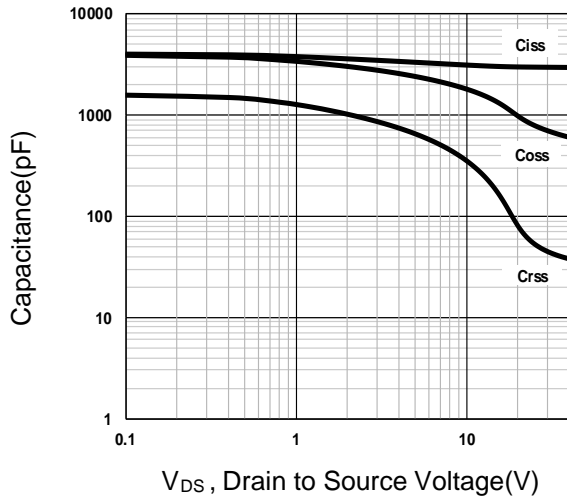


Fig. 7 Capacitance Characteristics

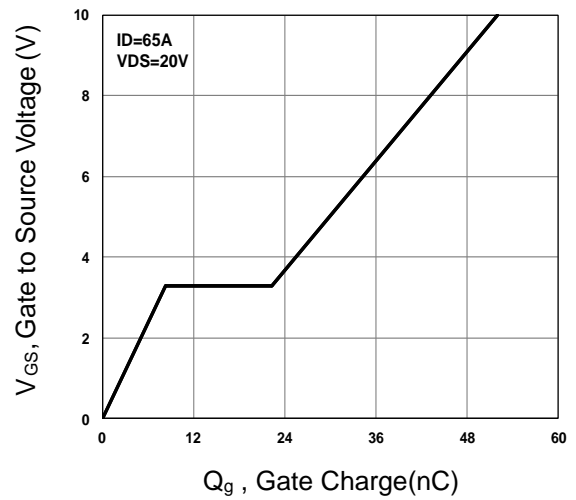


Fig. 8 Gate Charge Characteristics

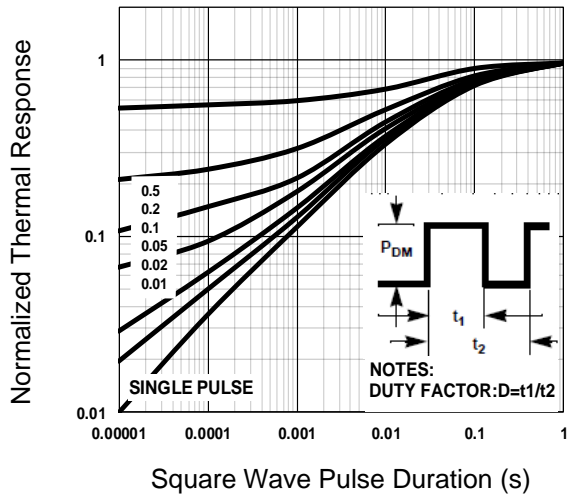


Fig. 9 Normalized Transient Impedance

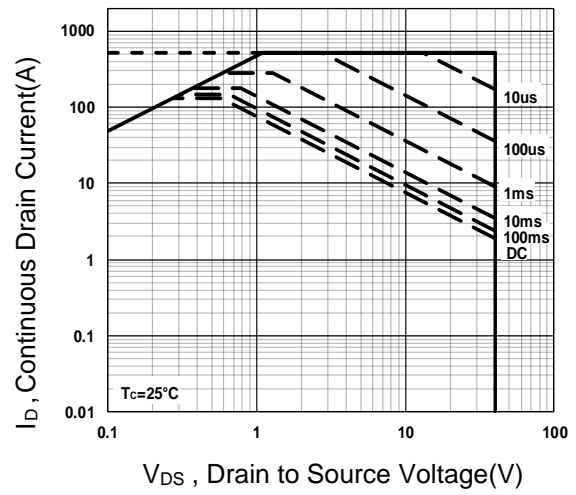


Fig. 10 Maximum Safe Operation Area

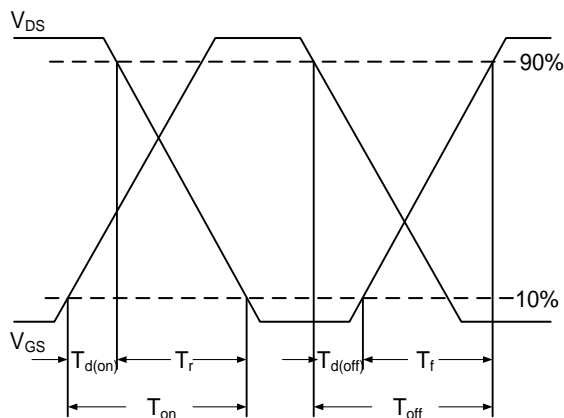


Fig. 11 Switching Time Waveform

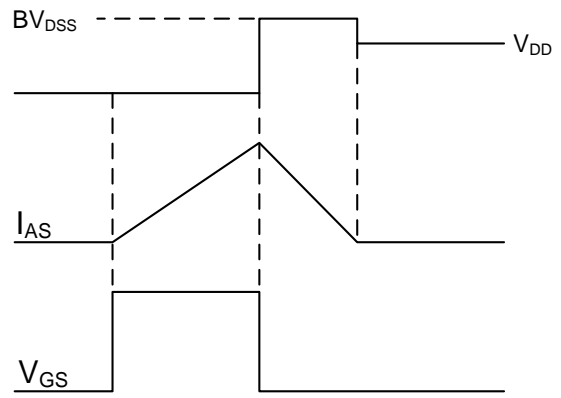
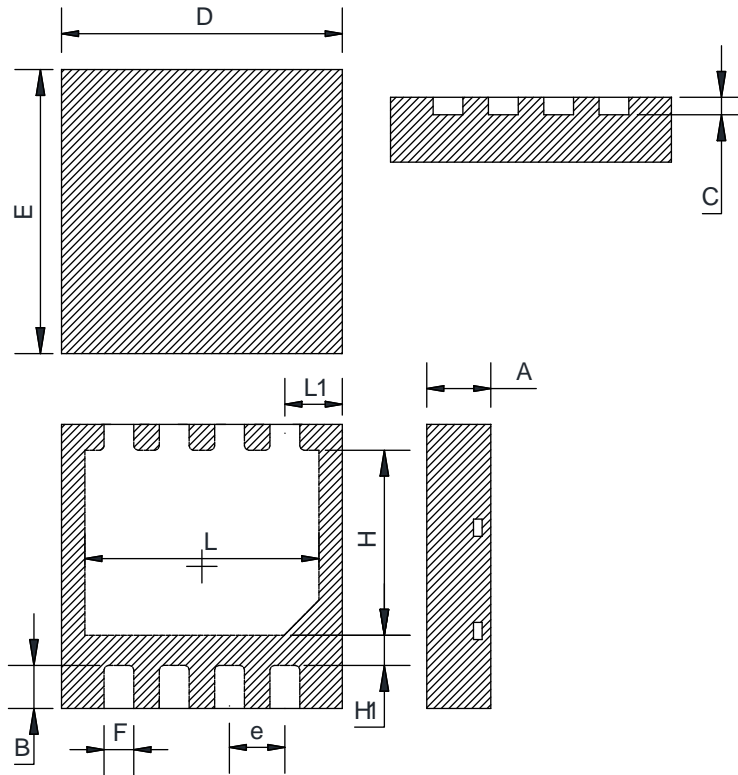


Fig. 12 EAS Waveform

DFN3.3X3.3-8L PACKAGE OUTLINE



**COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)**

Symbol	Min	Typ	Max
A	0.60	0.75	0.90
B	0.30	0.50	0.70
C	0.143	0.203	0.263
D	3.15	3.30	3.45
E	3.15	3.30	3.45
e	0.50	0.65	0.80
F	0.25	0.35	0.45
H	1.85	2.15	2.45
H1	0.20	0.35	0.50
L	2.35	2.75	3.15
L1	0.475	0.675	0.875

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